



Specification HW331A

SSC		CUSTOMER
Drawn	Approval	Approval

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1. Full Code of HIGH FLUX LED Series

Full code form : X₁ X₂ X₃ X₄ X₅ X₆ X₇X₈ - X₁₀X₁₁

1. Part Number

- X₁ : Model
- X₂ : Number of Die *1
- X₃ : Color
- X₄ : Lens Shape
- X₅ : Directivity
- X₆ : Revision Symbol
- X₇ : High Reliability *2
- X₈ : Surface coloring & Diffusion *3

*1, 2, 3 are added to the Product Type only in necessary cases.

2. Internal Number

- X₁₀
- X₁₁

3. Sticker Diagram on Box & Plastic Tube

HXXXXX

RANK : XXXX

QTY : 1200pcs

LOT : 20XX.XX.XX




SEOUL SEMICONDUCTOR CO., LTD



DEVICE HW331A



Hc14

LOT NO. 20XX.XX.XX



CAT Hc14 QTY 60 D/C 07XX





HW331A

Description

This revolutionary package design allows the lighting designer to reduce the number of LEDs required and provide a more uniform and unique illuminated appearance than with other LED solutions.

This package LEDs are designed for high current operation and high flux output application. But the package's design features better thermal management characteristics than other LED solutions. Because of these advantages, this product have many applications. Such as automotive tail, stop and turn signal lamps, and electronic signs etc.



HW331A

Features

- High flux output and high luminance
- Designed for high current operation
- Uniform color
- Low profile and low thermal resistance
- Packaged in tubes for use with automatic insertion equipment

Applications

- Automotive exterior lighting
- Electronic signs and signals
- Channel letter / lighting
- Decorative lighting
- Specialty Lighting



3. Absolute maximum ratings

Parameter	Symbol	Value	Unit
DC Forward Current	I_F	30	mA
Forward Peak Pulse Current	$I_{FP}^{[1]}$	100	mA
Reverse Voltage	V_R	5	V
Power Dissipation	P_D	120	mW
Operating Temperature	T_{opr}	-40 ~ 100	°C
Storage Temperature	T_{stg}	-40 ~ 100	°C
Solder Temperature	T_S	260°C for 5second ^[2]	°C

[1] $t \leq 0.1\text{ms}$, $D = 1/10$

[2] No closer than stopper.

4. Electric & Optical characteristics

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Luminous Flux ^[3]	Φ_V	IF=30mA	4.4	6	-	lm
Chromaticity Coordinate ^[4]	x, y	IF=30mA	x=0.31, y=0.31			-
Forward Voltage ^[5]	V_F	IF=30mA	-	3.4	4.0	V
View Angle	$2\theta_{1/2}$	IF=30mA	110			Deg.
Thermal Resistance	$R\theta_{J-P}$	IF=30mA	130			°C /W
Reverse Current	I_R	Vr=5V	-	-	5	μA

[3] SSC maintains a tolerance of $\pm 10\%$ on flux and power measurements.

[4] Correlated Color Temperature is derived from the CIE 1931 Chromaticity diagram.

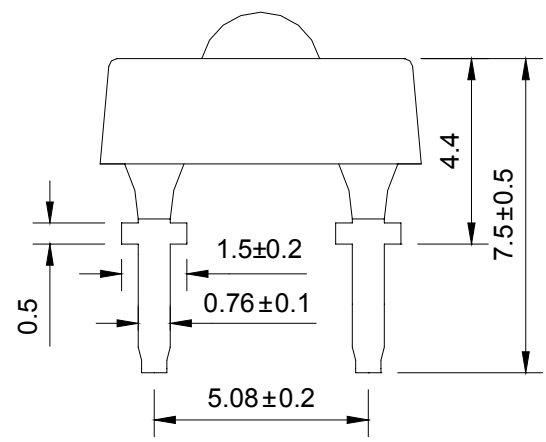
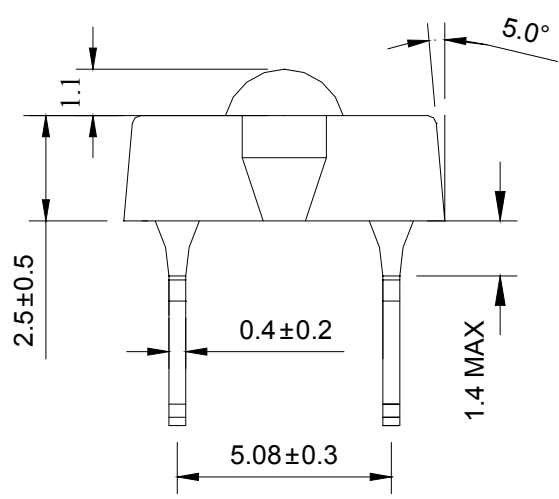
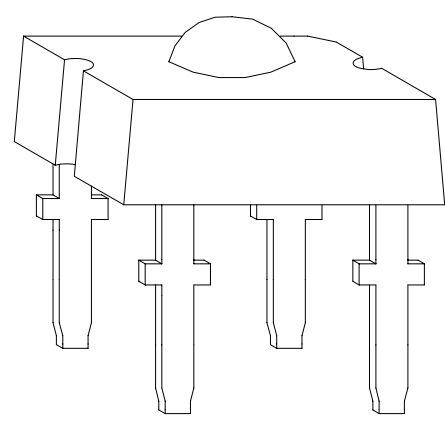
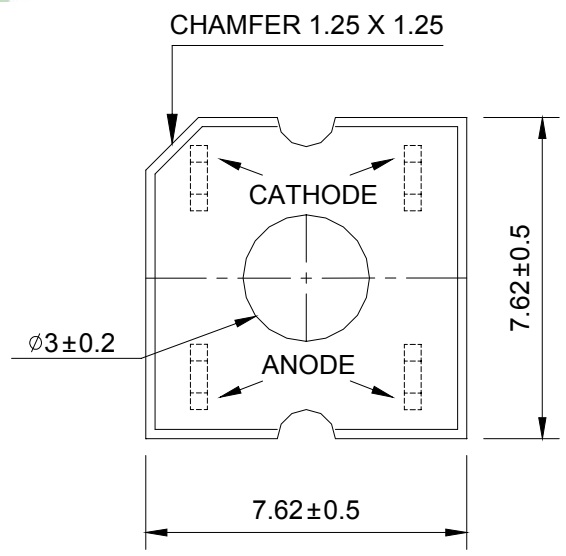
Color Coordinates Measurement allowance is ± 0.01

[5] A tolerance of $\pm 0.05\text{V}$ on forward voltage measurements.

[Note] All measurements were made under the standardized environment of SSC.

5.Outline Dimension

Unit : mm

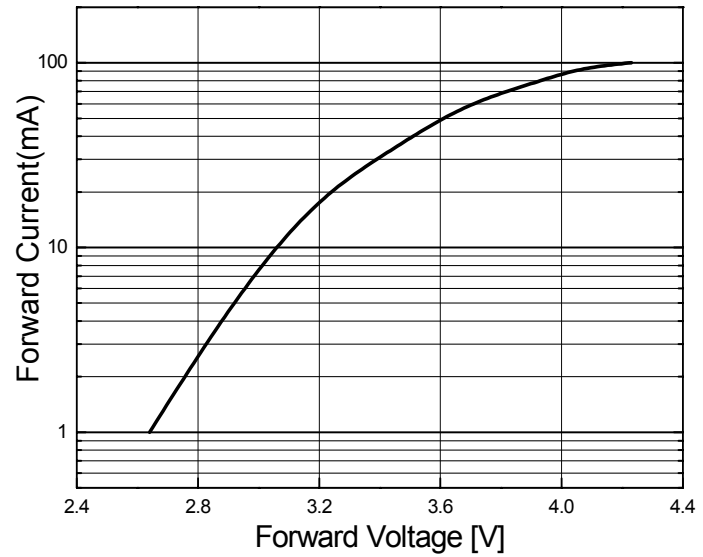


Notes : Protruded epoxy is 1.0mm maximum.

6. Optical characteristics

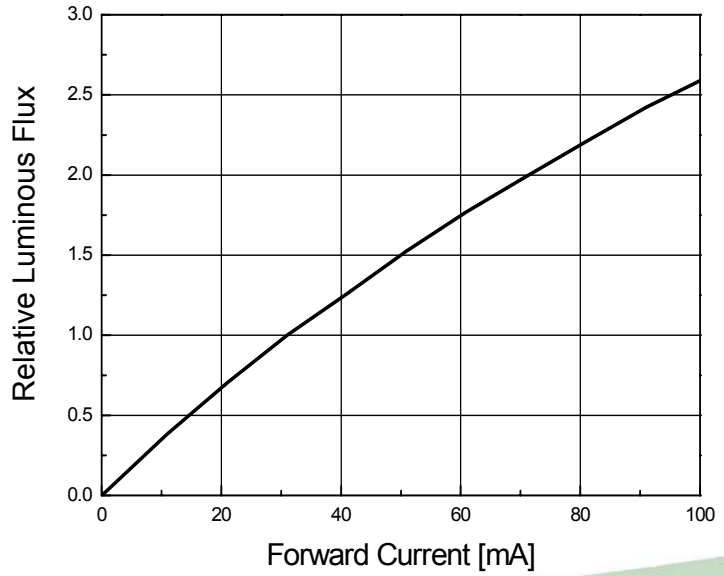
Forward Current vs. Forward Voltage

($T_a=25\text{ }^\circ\text{C}$)



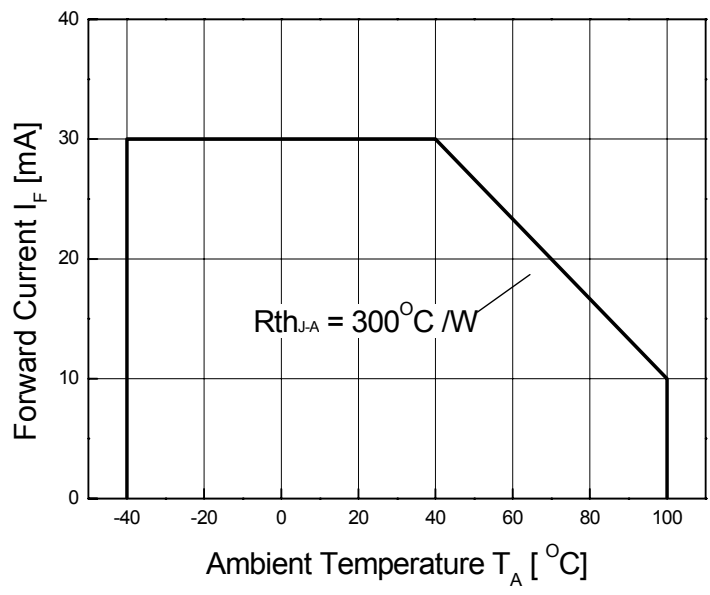
Relative Luminous Intensity vs Forward Current

($T_a=25\text{ }^\circ\text{C}$)



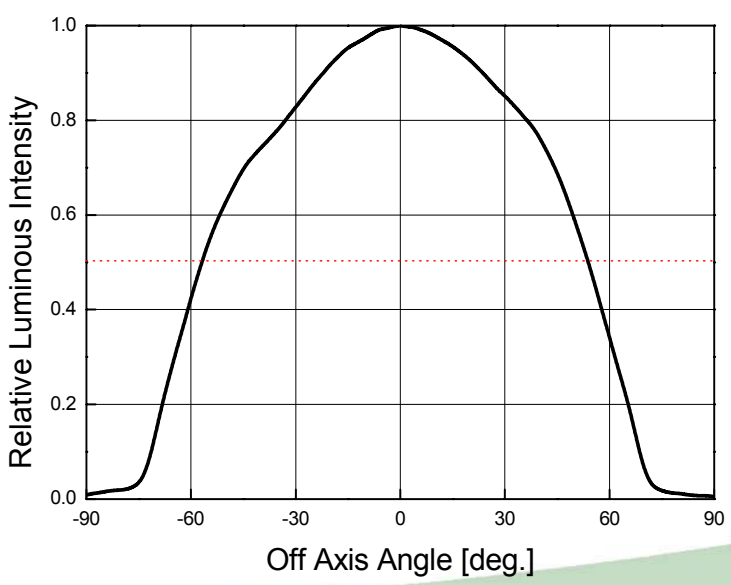
6. Optical characteristics

Ambient Temperature vs. Allowable Forward Current



Radiation Diagram

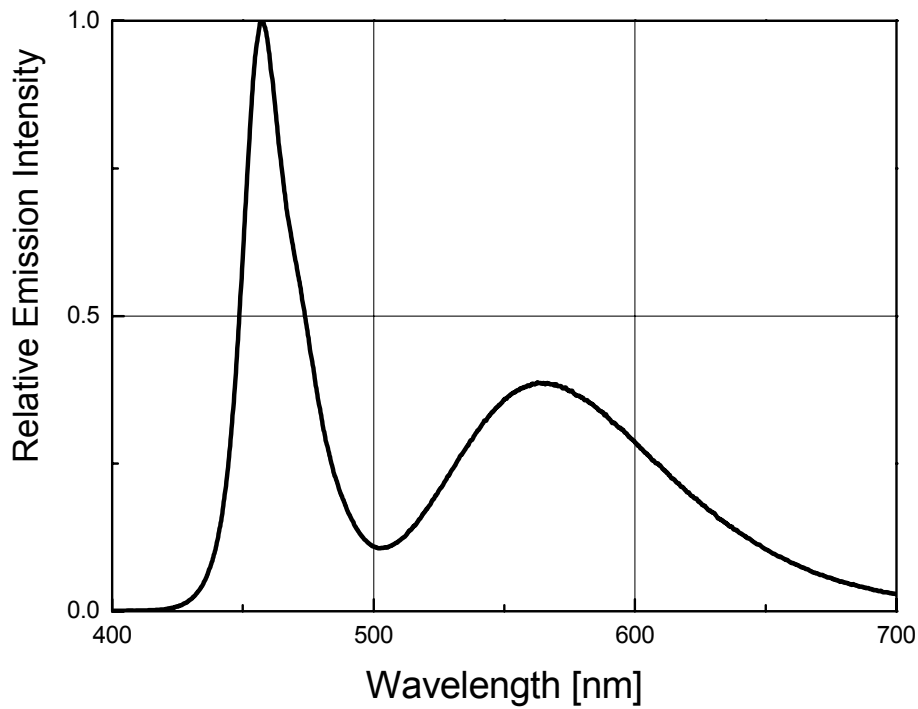
($T_a = 25^{\circ}\text{C}$)



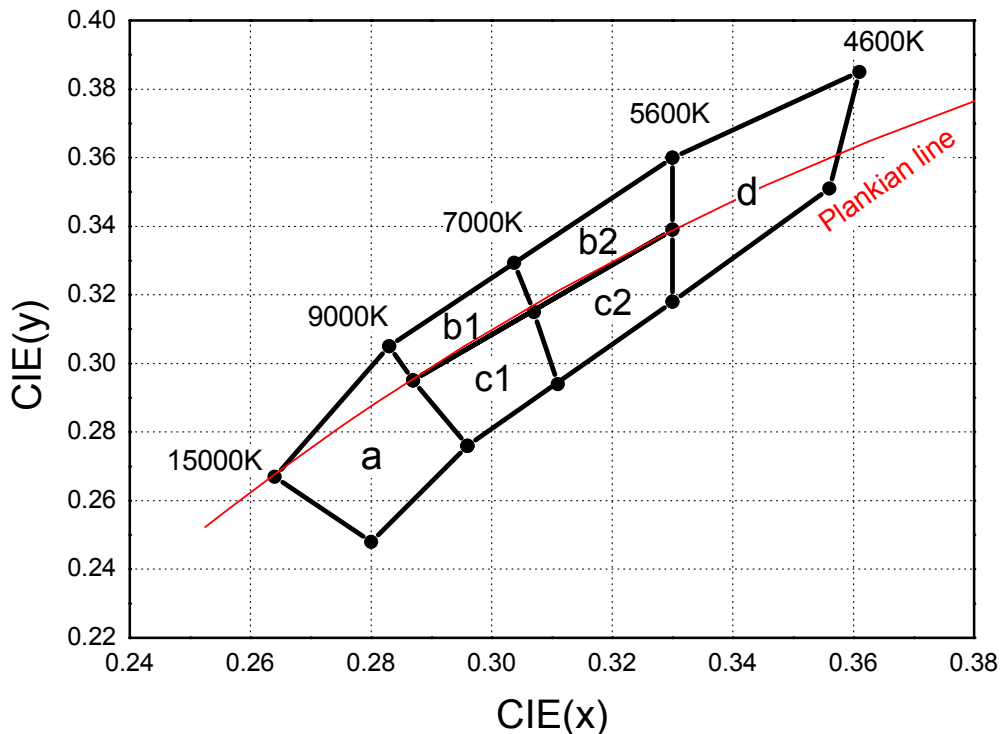
6. Optical characteristics

Spectrum

($T_a=25\text{ }^\circ\text{C}$)



7. Color & Binning



	Rank a			
x	0.264	0.280	0.296	0.283
y	0.267	0.248	0.276	0.305

	Rank b1			
x	0.287	0.283	0.304	0.307
y	0.295	0.305	0.330	0.315

	Rank b2			
x	0.307	0.304	0.330	0.330
y	0.315	0.330	0.360	0.339

	Rank c1			
x	0.296	0.287	0.307	0.311
y	0.276	0.295	0.315	0.294

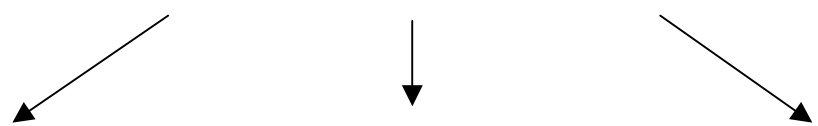
	Rank c2			
x	0.311	0.307	0.330	0.330
y	0.294	0.315	0.339	0.318

	Rank d			
x	0.330	0.330	0.356	0.361
y	0.360	0.318	0.351	0.385

Note : Color Coordinates Measurement allowance is ± 0.01

8. Rank of HW941A

Bin Code		
Luminous Flux	CIE	Forward Voltage
H	c1	4



Luminous Flux (lm) @ $I_F = 30\text{mA}$		
Bin Code	Min.	Max.
G	3.4	4.4
H	4.4	5.8
J	5.8	7.6
K	7.6	10.0

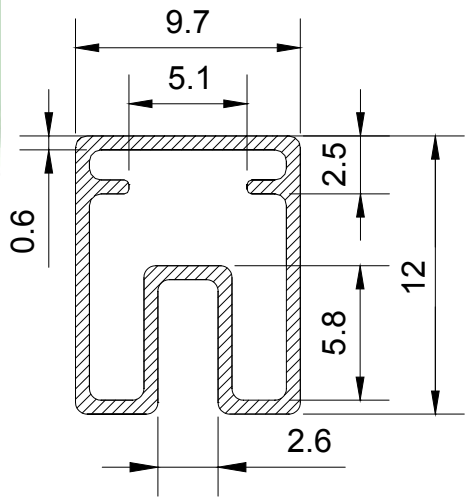
Color Rank @ $I_F = 30\text{mA}$
a
b1
b2
c1
c2
d

Forward Voltage (V) @ $I_F = 30\text{mA}$		
Bin Code	Min.	Max.
1	2.8	3.0
2	3.0	3.2
3	3.2	3.4
4	3.4	3.6
5	3.6	3.8
6	3.8	4.0
7	4.0	4.2

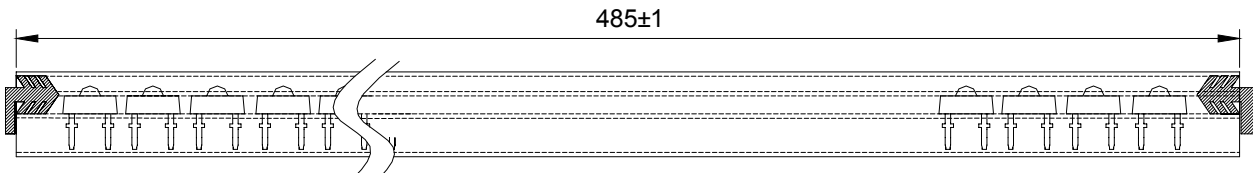
Available ranks

9. Packing

Unit : mm



Top view

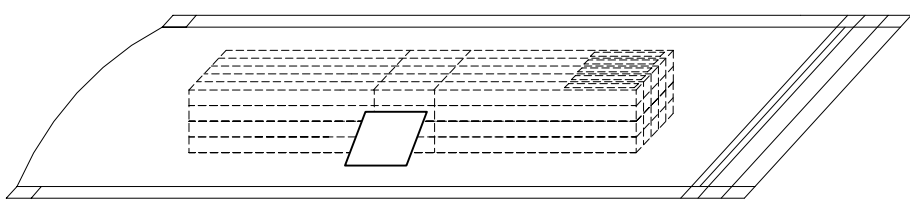


Side view

* Plastic tube
60pcs max/tube

9. Packing

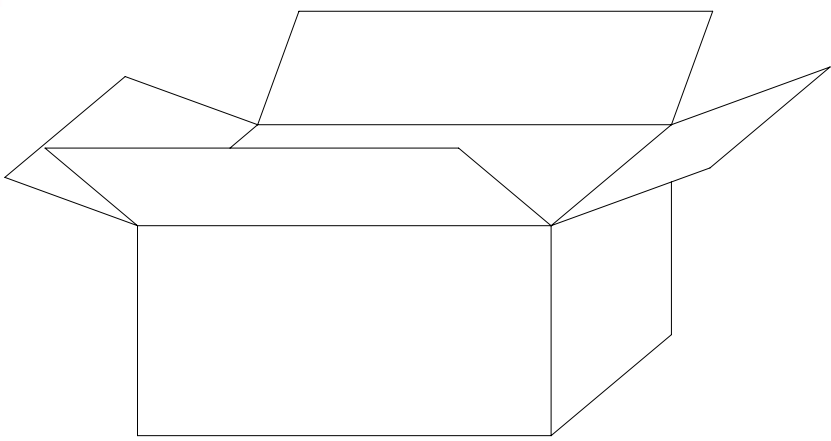
Unit : mm



1200pcs max/pack
(20tubes max/pack)

* Aluminum Sealing pack (in silica gel)

HXXXX	
RANK : XXXX	
QTY : 1200pcs	
LOT : 20XX.XX.XX	
SEOUL SEMICONDUCTOR CO., LTD	

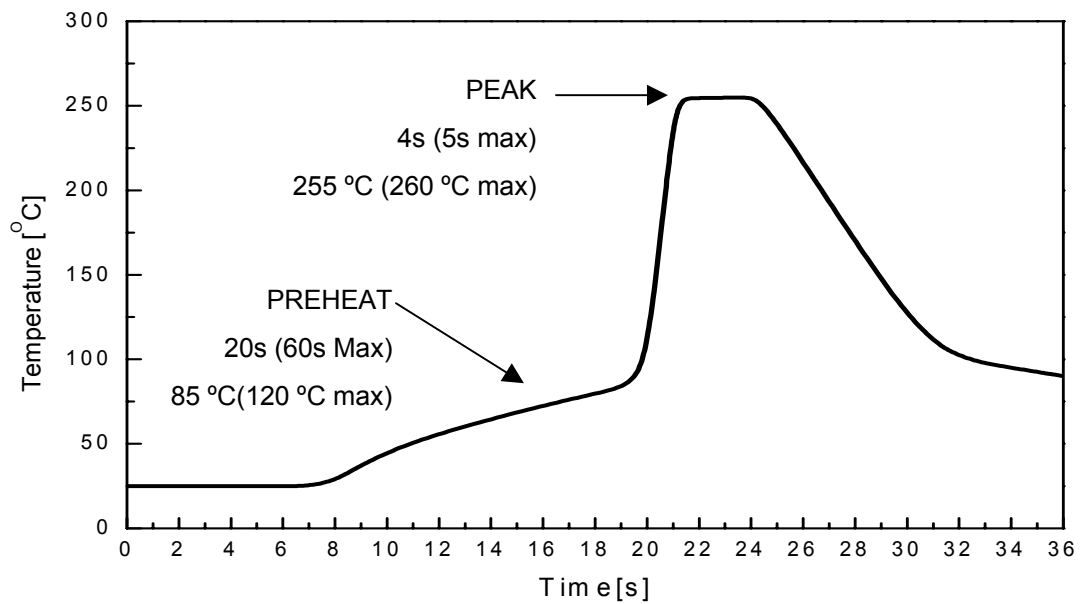


* Cardboard box (500x220x280)
(21600pcs max/box)
(18packs max/box)

10. Soldering

1) Recommended Wave Soldering Conditions / Profile

- Preliminary heating to be at 85°C(120 °C max) for 20 seconds(60 seconds max).
- Soldering heat to be at 255 °C (260°C max) for 4 seconds (5 seconds max.)
- Soak time above 200 °C is 5 seconds



2) Hand Soldering conditions

- Not more than 3 seconds at max. 350°C, under Soldering iron.

3) Caution

- Leadframes are silver plated copper alloy. This substance has a low thermal coefficient (easily conducts heat)
- No closer than 1.5mm from the base of the stopper.
- The LEDs must not be repositioned after soldering.
- Do not apply any stress to the lead particularly when heat.

Note : In case the soldered products are reused in soldering process, we don't guarantee the products.

11. Precaution for use

1) Storage

- Before opening the package

Avoid the absorption of moisture, we recommended to store High Flux LEDs in a dry box(or desiccator) with a desiccant . Otherwise, store them in the following environment:

Temperature : 5℃~30℃ Humidity : 50% max.

- After opening the package

a. Soldering should be done right after opening the package(within 24Hrs).

b. Keeping of a fraction

- Sealing

- Temperature : 5 ~ 40℃, Humidity : less than 30%

c. If the package has been opened more than 1week or the color of desiccant changes,

Components should be dried for 10-12hr at 60±5℃

- Any mechanical force or any excess vibration shall not be accepted to apply during cooling process to normal temp. after soldering.
- Avoid quick cooling
- Lead frames are silver plated copper alloy. The silver plate surface may be affected by environments which contains corrosive substances. Please avoid conditions which may cause the LEDs to corrode, tarnish or discolor.

2) Static Electricity

- Static Electricity and surge voltage damage the LEDs. So it is recommended that a wrist band or an anti-electrostatic glove be used when handling the LEDs.

- All devices, equipment and machinery must be properly grounded.

It is recommended precautions be taken against surge voltage to the equipment that mounts the LEDs.

3) Heat Generation

- Thermal is one of the important parameter to design the end product. Please consider the heat generation of the LEDs.

- The operating current should be decided after considering the ambient maximum temperature of LEDs.

4) Others

- The color of the LEDs is changed slightly an operating current and thermal.
- Anti radioactive ray design is not considered for the products listed here.
- Gallium arsenide is used in some of the products listed in this publication. These products are dangerous if they are burned or smashed in the process of disposal. It is also dangerous to drink the liquid or inhale the gas generated by such products when chemically disposed.
- This device should not be used in any type of fluid such as water, oil, organic solvent and etc. When washing is required, IPA(Isopropyl Alcohol) should be used.
- When the LEDs are illuminating, operating current should be decided after considering the junction temperature.
Cf.) Please refer *Ambient temperature vs. Forward Current* graph on page 5
- The appearance and specifications of the product may be modified for improvement without notice.

12. Reliability Test Item and Condition

Item	Condition	Note	Failures
Life Test	$T_a = RT, I_F = 30mA$	1000hrs	0/22
High Temperature Operating	$T_a = 85^{\circ}C, I_F = 10mA$	1000hrs	0/22
Low Temperature Operating	$T_a = -30^{\circ}C, I_F = 30mA$	1000hrs	0/22
Thermal Shock	$T_a = -40^{\circ}C$ (15min) ~ 100° (15min) (Transfer time : 10sec, 1Cycle = 30min)	100 cycles	0/40
Resistance to soldering Heat	$T_s = 255 \pm 5^{\circ}C, t = 4 \pm 1sec$	1 time	0/22
ESD (Human Body Model)	1kV, 1.5k Ω ; 100pF	1 time	0/22
High Temperature Storage	$T_a = 100^{\circ}C$	1000hrs	0/22
Low Temperature Storage	$T_a = -40^{\circ}C$	1000hrs	0/22
Temperature Humidity Storage	$T_a = 85^{\circ}C, RH = 85%$	1000hrs	0/22
Temperature Humidity Operating	$T_a = 85^{\circ}C, RH = 85%, I_F = 10mA$	500hrs	0/22

< Judging Criteria For Reliability Tests >

V_F	USL ^[1] X 1.2
I_R	USL X 2.0
Φ_V	LSL ^[2] X 0.7

Notes :

[1] USL : Upper Standard Level

[2] LSL : Lower Standard Level.